FEATURES

- Industry Standard Pinouts
- 60, 70 or 80ns RAS Access Time (tRAC)
- Static Column or Enhanced Page Mode
- RAS-Only Refresh, Hidden Refresh and CAS-before-RAS Refresh
- Separate CAS control for the 9th (parity) Data In/Data Out
- Commercial Voltage/Temperature Range
  - 4.5 - 5.5 Volts Vcc
  - 0 - 70°C Operating Temperature
- Available in either SIPP (Leaded) or SIMM (Leadless) configuration

See page 11 for Package and Pinout details

MM2800J8/J9 SERIES

Part Number	t_{RAC} [1]	t_{CAC} [2]	t_{AA} [3] (t_{CAA})	t_{RC} [4]	t_{PC} [5]	I_{CC} [6] (Standby)	I_{CC} [7] (Active)	Refresh [8] (t_{REF})
256K x 8/9 - STATIC COLUMN MODE								
MM2800J8X-06	60ns	11ns	32ns	121ns	35ns	20mA	600mA	4.4ms
MM2800J9X-06	60ns	11ns	32ns	121ns	35ns	23mA	670mA	4.4ms
MM2800J8X-07	70ns	12ns	35ns	136ns	40ns	20mA	560mA	4.4ms
MM2800J9X-07	70ns	12ns	35ns	136ns	40ns	23mA	630mA	4.4ms
MM2800J8X-08	80ns	13ns	40ns	151ns	45ns	20mA	520mA	4.4ms
MM2800J9X-08	80ns	13ns	40ns	151ns	45ns	23mA	585mA	4.4ms
256K x 8/9 - ENHANCED PAGE MODE								
MM2801J8X-06	60ns	11ns	32ns	121ns	37ns	20mA	600mA	4.4ms
MM2801J9X-06	60ns	11ns	32ns	121ns	37ns	23mA	670mA	4.4ms
MM2801J8X-07	70ns	12ns	35ns	136ns	41ns	20mA	560mA	4.4ms
MM2801J9X-07	70ns	12ns	35ns	136ns	41ns	23mA	630mA	4.4ms
MM2801J8X-08	80ns	13ns	40ns	151ns	46ns	20mA	520mA	4.4ms
MM2801J9X-08	80ns	13ns	40ns	151ns	46ns	23mA	585mA	4.4ms

NOTES:

1. tRAC defines maximum RAS Access Time.
2. tCAC defines maximum CAS Access Time.
3. tAA (alternatively tCAA) defines maximum Column Address Access Time.
4. tRC defines minimum Read or Write Cycle Time.
5. tPC defines minimum Enhanced Page Mode or Static Column Mode Cycle Time.
6. Icc (Standby) defines maximum Vcc supply current with RAS ≥ Vcc - 0.2V, other inputs at CMOS levels, 4.5 ≤ Vcc ≤ 5.5V and 0°C ≤ Ta ≤ 70°C.
7. Icc (Active) defines maximum Vcc supply current under normal operation with tRC = tRC min., 4.5 ≤ Vcc ≤ 5.5V and 0°C ≤ Ta ≤ 70°C.
8. tREF defines the Refresh Interval during which all internal rows (256) must be refreshed.
9. MM2800 Family devices are mounted on epoxy-glass 4-layer boards and include 8 or 9 pieces of 0.22 µF decoupling capacitors mounted underneath the memory devices. SIMM (Leadless) module connectors are finished with solder plating over copper. SIPP leads are solder plated.

ORDERING INFORMATION:

MM280XJXX - XX

- SPEED: 06: 60ns tRAC; 07: 70ns tRAC; 08: 80ns tRAC
- PACKAGE: L: SIPP (Leaded) (Note 9); S: SIMM (Leadless) (Note 9)
- ORGANIZATION: 8: x8; 9: x9
- OPERATING MODE: 0: Static Column Mode; 1: Enhanced Page Mode